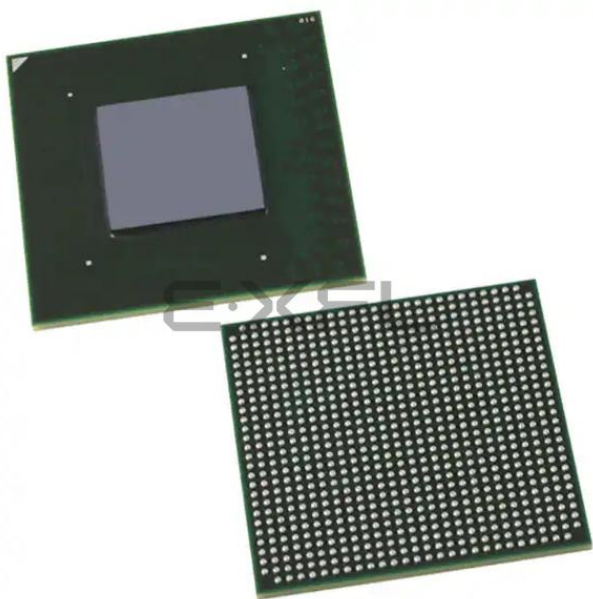




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Details

Product Status	Obsolete
Number of LABs/CLBs	4964
Number of Logic Elements/Cells	118143
Total RAM Bits	8315904
Number of I/O	372
Number of Gates	-
Voltage - Supply	0.87V ~ 0.93V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	780-BBGA, FCBGA
Supplier Device Package	780-FBGA (29x29)
Purchase URL	https://www.e-xfl.com/product-detail/intel/ep2agx125ef29c4

Table 1–5. Recommended Operating Conditions for Arria II GX Devices (Note 1) (Part 2 of 2)

Symbol	Description	Condition	Minimum	Typical	Maximum	Unit
t_{RAMP}	Power Supply Ramp time	Normal POR	0.05	—	100	ms
		Fast POR	0.05	—	4	ms

Notes to Table 1–5:

- (1) For more information about supply pin connections, refer to the *Arria II Device Family Pin Connection Guidelines*.
- (2) Altera recommends a 3.0-V nominal battery voltage when connecting V_{CCBAT} to a battery for volatile key backup. If you do not use the volatile security key, you may connect the V_{CCBAT} to either GND or a 3.0-V power supply.
- (3) V_{CCPD} must be 2.5-V for I/O banks with 2.5-V and lower V_{CCIO} , 3.0-V for 3.0-V V_{CCIO} , and 3.3-V for 3.3-V V_{CCIO} .
- (4) V_{CCIO} for 3C and 8C I/O banks where the configuration pins reside only supports 3.3-, 3.0-, 2.5-, or 1.8-V voltage levels.

Table 1–6 lists the recommended operating conditions for Arria II GZ devices.

Table 1–6. Recommended Operating Conditions for Arria II GZ Devices (Note 6) (Part 1 of 2)

Symbol	Description	Condition	Minimum	Typical	Maximum	Unit
V_{CC}	Core voltage and periphery circuitry power supply	—	0.87	0.90	0.93	V
V_{CCCB}	Supplies power for the configuration RAM bits	—	1.45	1.50	1.55	V
V_{CCAUX}	Auxiliary supply	—	2.375	2.5	2.625	V
V_{CCPD} (2)	I/O pre-driver (3.0 V) power supply	—	2.85	3.0	3.15	V
	I/O pre-driver (2.5 V) power supply	—	2.375	2.5	2.625	V
V_{CCIO}	I/O buffers (3.0 V) power supply	—	2.85	3.0	3.15	V
	I/O buffers (2.5 V) power supply	—	2.375	2.5	2.625	V
	I/O buffers (1.8 V) power supply	—	1.71	1.8	1.89	V
	I/O buffers (1.5 V) power supply	—	1.425	1.5	1.575	V
	I/O buffers (1.2 V) power supply	—	1.14	1.2	1.26	V
V_{CCPGM}	Configuration pins (3.0 V) power supply	—	2.85	3.0	3.15	V
	Configuration pins (2.5 V) power supply	—	2.375	2.5	2.625	V
	Configuration pins (1.8 V) power supply	—	1.71	1.8	1.89	V
$V_{\text{CCA_PLL}}$	PLL analog voltage regulator power supply	—	2.375	2.5	2.625	V
$V_{\text{CCD_PLL}}$	PLL digital voltage regulator power supply	—	0.87	0.90	0.93	V
$V_{\text{CC_CLKIN}}$	Differential clock input power supply	—	2.375	2.5	2.625	V
V_{CCBAT} (1)	Battery back-up power supply (For design security volatile key register)	—	1.2	—	3.3	V
V_{I}	DC input voltage	—	–0.5	—	3.6	V
V_{O}	Output voltage	—	0	—	V_{CCIO}	V
$V_{\text{CCA_L}}$	Transceiver high voltage power (left side)	—	2.85/2.375	3.0/2.5 (4)	3.15/2.625	V
$V_{\text{CCA_R}}$	Transceiver high voltage power (right side)	—				
$V_{\text{CCHIP_L}}$	Transceiver HIP digital power (left side)	—	0.87	0.9	0.93	V
$V_{\text{CCR_L}}$	Receiver power (left side)	—	1.05	1.1	1.15	V
$V_{\text{CCR_R}}$	Receiver power (right side)	—	1.05	1.1	1.15	V
$V_{\text{CCT_L}}$	Transmitter power (left side)	—	1.05	1.1	1.15	V
$V_{\text{CCT_R}}$	Transmitter power (right side)	—	1.05	1.1	1.15	V

Table 1-10 lists the bus hold specifications for Arria II GZ devices.

Table 1-10. Bus Hold Parameters for Arria II GZ Devices

Parameter	Symbol	Cond.	V _{CCIO} (V)										Unit
			1.2		1.5		1.8		2.5		3.0		
			Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
Bus-hold Low sustaining current	I _{SUSL}	V _{IN} > V _{IL} (max.)	22.5	—	25.0	—	30.0	—	50.0	—	70.0	—	μA
Bus-hold High sustaining current	I _{SUSH}	V _{IN} < V _{IH} (min.)	-22.5	—	-25.0	—	-30.0	—	-50.0	—	-70.0	—	μA
Bus-hold Low overdrive current	I _{ODL}	0V < V _{IN} < V _{CCIO}	—	120	—	160	—	200	—	300	—	500	μA
Bus-hold High overdrive current	I _{ODH}	0V < V _{IN} < V _{CCIO}	—	-120	—	-160	—	-200	—	-300	—	-500	μA
Bus-hold trip point	V _{TRIP}	—	0.45	0.95	0.50	1.00	0.68	1.07	0.70	1.70	0.80	2.00	V

OCT Specifications

Table 1-11 lists the Arria II GX device and differential OCT with and without calibration accuracy.

Table 1-11. OCT With and Without Calibration Specification for Arria II GX Device I/Os (Note 1) (Part 1 of 2)

Symbol	Description	Conditions (V)	Calibration Accuracy		Unit
			Commercial	Industrial	
25- Ω R_S 3.0, 2.5	25- Ω series OCT without calibration	$V_{CCIO} = 3.0, 2.5$	± 30	± 40	%
50- Ω R_S 3.0, 2.5	50- Ω series OCT without calibration	$V_{CCIO} = 3.0, 2.5$	± 30	± 40	%
25- Ω R_S 1.8	25- Ω series OCT without calibration	$V_{CCIO} = 1.8$	± 40	± 50	%
50- Ω R_S 1.8	50- Ω series OCT without calibration	$V_{CCIO} = 1.8$	± 40	± 50	%
25- Ω R_S 1.5, 1.2	25- Ω series OCT without calibration	$V_{CCIO} = 1.5, 1.2$	± 50	± 50	%
50- Ω R_S 1.5, 1.2	50- Ω series OCT without calibration	$V_{CCIO} = 1.5, 1.2$	± 50	± 50	%
25- Ω R_S 3.0, 2.5, 1.8, 1.5, 1.2	25- Ω series OCT with calibration	$V_{CCIO} = 3.0, 2.5, 1.8, 1.5, 1.2$	± 10	± 10	%

Table 1–23. Single-Ended I/O Standards for Arria II GZ Devices (Part 2 of 2)

I/O Standard	V_{CCIO} (V)			V_{IL} (V)		V_{IH} (V)		V_{OL} (V)	V_{OH} (V)	I_{OL} (mA)	I_{OH} (mA)
	Min	Typ	Max	Min	Max	Min	Max	Max	Min		
1.2 V	1.14	1.2	1.26	-0.3	$0.35 \times V_{CCIO}$	$0.65 \times V_{CCIO}$	$V_{CCIO} + 0.3$	$0.25 \times V_{CCIO}$	$0.75 \times V_{CCIO}$	2	-2
3.0-V PCI	2.85	3	3.15	—	$0.3 \times V_{CCIO}$	$0.5 \times V_{CCIO}$	3.6	$0.1 \times V_{CCIO}$	$0.9 \times V_{CCIO}$	1.5	-0.5
3.0-V PCI-X	2.85	3	3.15	—	$0.35 \times V_{CCIO}$	$0.5 \times V_{CCIO}$	—	$0.1 \times V_{CCIO}$	$0.9 \times V_{CCIO}$	1.5	-0.5

Table 1–24 lists the single-ended SSTL and HSTL I/O reference voltage specifications for Arria II GX devices.

Table 1–24. Single-Ended SSTL and HSTL I/O Reference Voltage Specifications for Arria II GX Devices

I/O Standard	V_{CCIO} (V)			V_{REF} (V)			V_{TT} (V)		
	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max
SSTL-2 Class I, II	2.375	2.5	2.625	$0.49 \times V_{CCIO}$	$0.5 \times V_{CCIO}$	$0.51 \times V_{CCIO}$	$V_{REF} - 0.04$	V_{REF}	$V_{REF} + 0.04$
SSTL-18 Class I, II	1.71	1.8	1.89	0.833	0.9	0.969	$V_{REF} - 0.04$	V_{REF}	$V_{REF} + 0.04$
SSTL-15 Class I, II	1.425	1.5	1.575	$0.47 \times V_{CCIO}$	$0.5 \times V_{CCIO}$	$0.53 \times V_{CCIO}$	$0.47 \times V_{CCIO}$	$0.5 \times V_{CCIO}$	$0.53 \times V_{CCIO}$
HSTL-18 Class I, II	1.71	1.8	1.89	0.85	0.9	0.95	0.85	0.9	0.95
HSTL-15 Class I, II	1.425	1.5	1.575	0.71	0.75	0.79	0.71	0.75	0.79
HSTL-12 Class I, II	1.14	1.2	1.26	$0.48 \times V_{CCIO}$	$0.5 \times V_{CCIO}$	$0.52 \times V_{CCIO}$	—	$V_{CCIO}/2$	—

Table 1–25 lists the single-ended SSTL and HSTL I/O reference voltage specifications for Arria II GZ devices.

Table 1–25. Single-Ended SSTL and HSTL I/O Reference Voltage Specifications for Arria II GZ Devices

I/O Standard	V_{CCIO} (V)			V_{REF} (V)			V_{TT} (V)		
	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max
SSTL-2 Class I, II	2.375	2.5	2.625	$0.49 \times V_{CCIO}$	$0.5 \times V_{CCIO}$	$0.51 \times V_{CCIO}$	$V_{REF} - 0.04$	V_{REF}	$V_{REF} + 0.04$
SSTL-18 Class I, II	1.71	1.8	1.89	0.833	0.9	0.969	$V_{REF} - 0.04$	V_{REF}	$V_{REF} + 0.04$
SSTL-15 Class I, II	1.425	1.5	1.575	$0.47 \times V_{CCIO}$	$0.5 \times V_{CCIO}$	$0.53 \times V_{CCIO}$	$0.47 \times V_{CCIO}$	V_{REF}	$0.53 \times V_{CCIO}$
HSTL-18 Class I, II	1.71	1.8	1.89	0.85	0.9	0.95	—	$V_{CCIO}/2$	—
HSTL-15 Class I, II	1.425	1.5	1.575	0.68	0.75	0.9	—	$V_{CCIO}/2$	—
HSTL-12 Class I, II	1.14	1.2	1.26	$0.47 \times V_{CCIO}$	$0.5 \times V_{CCIO}$	$0.53 \times V_{CCIO}$	—	$V_{CCIO}/2$	—

Table 1-27. Single-Ended SSTL and HSTL I/O Standards Signal Specifications for Arria II GZ Devices (Part 2 of 2)

I/O Standard	$V_{IL(DC)} (V)$		$V_{IH(DC)} (V)$		$V_{IL(AC)} (V)$	$V_{IH(AC)} (V)$	$V_{OL} (V)$	$V_{OH} (V)$	$I_{OL} (mA)$	$I_{OH} (mA)$
	Min	Max	Min	Max	Max	Min	Max	Min		
SSTL-15 Class II	—	$V_{REF} - 0.1$	$V_{REF} + 0.1$	—	$V_{REF} - 0.175$	$V_{REF} + 0.175$	$0.2 \times V_{CCIO}$	$0.8 \times V_{CCIO}$	16	-16
HSTL-18 Class I	—	$V_{REF} - 0.1$	$V_{REF} + 0.1$	—	$V_{REF} - 0.2$	$V_{REF} + 0.2$	0.4	$V_{CCIO} - 0.4$	8	-8
HSTL-18 Class II	—	$V_{REF} - 0.1$	$V_{REF} + 0.1$	—	$V_{REF} - 0.2$	$V_{REF} + 0.2$	0.4	$V_{CCIO} - 0.4$	16	-16
HSTL-15 Class I	—	$V_{REF} - 0.1$	$V_{REF} + 0.1$	—	$V_{REF} - 0.2$	$V_{REF} + 0.2$	0.4	$V_{CCIO} - 0.4$	8	-8
HSTL-15 Class II	—	$V_{REF} - 0.1$	$V_{REF} + 0.1$	—	$V_{REF} - 0.2$	$V_{REF} + 0.2$	0.4	$V_{CCIO} - 0.4$	16	-16
HSTL-12 Class I	-0.15	$V_{REF} - 0.08$	$V_{REF} + 0.08$	$V_{CCIO} + 0.15$	$V_{REF} - 0.15$	$V_{REF} + 0.15$	$0.25 \times V_{CCIO}$	$0.75 \times V_{CCIO}$	8	-8
HSTL-12 Class II	-0.15	$V_{REF} - 0.08$	$V_{REF} + 0.08$	$V_{CCIO} + 0.15$	$V_{REF} - 0.15$	$V_{REF} + 0.15$	$0.25 \times V_{CCIO}$	$0.75 \times V_{CCIO}$	16	-16

Table 1-28 lists the differential SSTL I/O standards for Arria II GX devices.

Table 1-28. Differential SSTL I/O Standards for Arria II GX Devices

I/O Standard	$V_{CCIO} (V)$			$V_{SWING(DC)} (V)$		$V_{X(AC)} (V)$			$V_{SWING(AC)} (V)$		$V_{OX(AC)} (V)$		
	Min	Typ	Max	Min	Max	Min	Typ	Max	Min	Max	Min	Typ	Max
SSTL-2 Class I, II	2.375	2.5	2.625	0.36	V_{CCIO}	$V_{CCIO}/2 - 0.2$	—	$V_{CCIO}/2 + 0.2$	0.7	V_{CCIO}	$V_{CCIO}/2 - 0.15$	—	$V_{CCIO}/2 + 0.15$
SSTL-18 Class I, II	1.71	1.8	1.89	0.25	V_{CCIO}	$V_{CCIO}/2 - 0.175$	—	$V_{CCIO}/2 + 0.175$	0.5	V_{CCIO}	$V_{CCIO}/2 - 0.125$	—	$V_{CCIO}/2 + 0.125$
SSTL-15 Class I, II	1.425	1.5	1.575	0.2	—	—	$V_{CCIO}/2$	—	0.35	—	—	$V_{CCIO}/2$	—

Table 1-29 lists the differential SSTL I/O standards for Arria II GZ devices

Table 1-29. Differential SSTL I/O Standards for Arria II GZ Devices

I/O Standard	$V_{CCIO} (V)$			$V_{SWING(DC)} (V)$		$V_{X(AC)} (V)$			$V_{SWING(AC)} (V)$		$V_{OX(AC)} (V)$		
	Min	Typ	Max	Min	Max	Min	Typ	Max	Min	Max	Min	Typ	Max
SSTL-2 Class I, II	2.375	2.5	2.625	0.3	$V_{CCIO} + 0.6$	$V_{CCIO}/2 - 0.2$	—	$V_{CCIO}/2 + 0.2$	0.62	$V_{CCIO} + 0.6$	$V_{CCIO}/2 - 0.15$	—	$V_{CCIO}/2 + 0.15$
SSTL-18 Class I, II	1.71	1.8	1.89	0.25	$V_{CCIO} + 0.6$	$V_{CCIO}/2 - 0.175$	—	$V_{CCIO}/2 + 0.175$	0.5	$V_{CCIO} + 0.6$	$V_{CCIO}/2 - 0.125$	—	$V_{CCIO}/2 + 0.125$
SSTL-15 Class I, II	1.425	1.5	1.575	0.2	—	—	$V_{CCIO}/2$	—	0.35	—	—	$V_{CCIO}/2$	—

Switching Characteristics

This section provides performance characteristics of the Arria II GX and GZ core and periphery blocks for commercial grade devices. The following tables are considered final and are based on actual silicon characterization and testing. These numbers reflect the actual performance of the device under worst-case silicon process, voltage, and junction temperature conditions.

Transceiver Performance Specifications

Table 1–34 lists the Arria II GX transceiver specifications.

Table 1–34. Transceiver Specifications for Arria II GX Devices (Note 1) (Part 1 of 7)

Symbol/ Description	Condition	I3			C4			C5 and I5			C6			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
Reference Clock														
Supported I/O Standards	1.2-V PCML, 1.5-V PCML, 2.5-V PCML, Differential LVPECL, LVDS, and HCSL													
Input frequency from REFCLK input pins	—	50	—	622.08	50	—	622.08	50	—	622.08	50	—	622.08	MHz
Input frequency from PLD input	—	50	—	200	50	—	200	50	—	200	50	—	200	MHz
Absolute V _{MAX} for a REFCLK pin	—	—	—	2.2	—	—	2.2	—	—	2.2	—	—	2.2	V
Absolute V _{MIN} for a REFCLK pin	—	−0.3	—	—	−0.3	—	—	−0.3	—	—	−0.3	—	—	V
Rise/fall time (2)	—	—	—	0.2	—	—	0.2	—	—	0.2	—	—	0.2	UI
Duty cycle	—	45	—	55	45	—	55	45	—	55	45	—	55	%
Peak-to-peak differential input voltage	—	200	—	2000	200	—	2000	200	—	2000	200	—	2000	mV
Spread-spectrum modulating clock frequency	PCIe	30	—	33	30	—	33	30	—	33	30	—	33	kHz

Table 1–34. Transceiver Specifications for Arria II GX Devices (Note 1) (Part 7 of 7)

Symbol/ Description	Condition	I3			C4			C5 and I5			C6			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
Digital reset pulse width	—	Minimum is 2 parallel clock cycles												

Notes to Table 1–34:

- (1) For AC-coupled links, the on-chip biasing circuit is switched off before and during configuration. Ensure that input specifications are not violated during this period.
- (2) The rise/fall time is specified from 20% to 80%.
- (3) To calculate the REFCLK rms phase jitter requirement at reference clock frequencies other than 100 MHz, use the following formula:
REFCLK rms phase jitter at f (MHz) = REFCLK rms phase jitter at 100 MHz * 100/f.
- (4) The minimum `reconfig_clk` frequency is 2.5 MHz if the transceiver channel is configured in **Transmitter only** mode. The minimum `reconfig_clk` frequency is 37.5 MHz if the transceiver channel is configured in **Receiver only** or **Receiver and Transmitter** mode. For more information, refer to [AN 558: Implementing Dynamic Reconfiguration in Arria II Devices](#).
- (5) If your design uses more than one dynamic reconfiguration controller instances (`altgx_reconfig`) to control the transceiver channels (`altgx`) physically located on the same side of the device, and if you use different `reconfig_clk` sources for these `altgx_reconfig` instances, the delta time between any two of these `reconfig_clk` sources becoming stable must not exceed the maximum specification listed.
- (6) The device cannot tolerate prolonged operation at this absolute maximum.
- (7) You must use the 1.1-V RX V_{ICM} setting if the input serial data standard is LVDS and the link is DC-coupled.
- (8) The rate matcher supports only up to ± 300 parts per million (ppm).
- (9) Time taken to `rx_pll_locked` goes high from `rx_analogreset` de-assertion. Refer to [Figure 1–1](#).
- (10) The time in which the CDR must be kept in lock-to-reference mode after `rx_pll_locked` goes high and before `rx_locktodata` is asserted in manual mode. Refer to [Figure 1–1](#).
- (11) The time taken to recover valid data after the `rx_locktodata` signal is asserted in manual mode. Refer to [Figure 1–1](#).
- (12) The time taken to recover valid data after the `rx_freqlocked` signal goes high in automatic mode. Refer to [Figure 1–2](#).
- (13) To support data rates lower than the minimum specification through oversampling, use the CDR in LTR mode only.

Table 1–35 lists the transceiver specifications for Arria II GZ devices.

Table 1–35. Transceiver Specifications for Arria II GZ Devices (Part 1 of 5)

Symbol/ Description	Conditions	–C3 and –I3 (1)			–C4 and –I4			Unit
		Min	Typ	Max	Min	Typ	Max	
Reference Clock								
Supported I/O Standards	1.2-V PCML, 1.5-V PCML, 2.5-V PCML, Differential LVPECL, LVDS, and HCSL							
Input frequency from REFCLK input pins	—	50	—	697	50	—	637.5	MHz
Phase frequency detector (CMU PLL and receiver CDR)	—	50	—	325	50	—	325	MHz
Absolute V _{MAX} for a REFCLK pin	—	—	—	1.6	—	—	1.6	V
Operational V _{MAX} for a REFCLK pin	—	—	—	1.5	—	—	1.5	V
Absolute V _{MIN} for a REFCLK pin	—	-0.4	—	—	-0.4	—	—	V
Rise/fall time (2)	—	—	—	0.2	—	—	0.2	UI
Duty cycle	—	45	—	55	45	—	55	%
Peak-to-peak differential input voltage	—	200	—	1600	200	—	1600	mV
Spread-spectrum modulating clock frequency	PCIe	30	—	33	30	—	33	kHz
Spread-spectrum downspread	PCIe	—	0 to -0.5%	—	—	0 to -0.5%	—	—
On-chip termination resistors	—	—	100	—	—	100	—	Ω
V _{ICM} (AC coupled)	—	1100 ± 10%			1100 ± 10%			mV
V _{ICM} (DC coupled)	HCSL I/O standard for PCIe reference clock	250	—	550	250	—	550	mV
Transmitter REFCLK Phase Noise	10 Hz	—	—	-50	—	—	-50	dBc/Hz
	100 Hz	—	—	-80	—	—	-80	dBc/Hz
	1 KHz	—	—	-110	—	—	-110	dBc/Hz
	10 KHz	—	—	-120	—	—	-120	dBc/Hz
	100 KHz	—	—	-120	—	—	-120	dBc/Hz
	≥ 1 MHz	—	—	-130	—	—	-130	dBc/Hz
Transmitter REFCLK Phase Jitter (rms) for 100 MHz REFCLK (3)	10 KHz to 20 MHz	—	—	3	—	—	3	ps
R _{REF}	—	—	2000 ± 1%	—	—	2000 ± 1%	—	Ω

Table 1-35. Transceiver Specifications for Arria II GZ Devices (Part 3 of 5)

Symbol/ Description	Conditions	–C3 and –I3 (1)			–C4 and –I4			Unit
		Min	Typ	Max	Min	Typ	Max	
Receiver DC Coupling Support	—	For more information about receiver DC coupling support, refer to the “DC-Coupled Links” section in the <i>Transceiver Architecture for Arria II Devices</i> chapter.						
Differential on-chip termination resistors	85–Ω setting	85 ± 20%			85 ± 20%			Ω
	100–Ω setting	100 ± 20%			100 ± 20%			Ω
	120–Ω setting	120 ± 20%			120 ± 20%			Ω
	150–Ω setting	150 ± 20%			150 ± 20%			Ω
Differential and common mode return loss	PCIe (Gen 1 and Gen 2), XAUI, HiGig+, CEI SR/LR, SRIO SR/LR, CPRI LV/HV, OBSAI, SATA	Compliant						—
Programmable PPM detector (9)	—	± 62.5, 100, 125, 200, 250, 300, 500, 1,000						ppm
Run length	—	—	—	200	—	—	200	UI
Programmable equalization	—	—	—	16	—	—	16	dB
t _{LTR} (10)	—	—	—	75	—	—	75	μs
t _{LTR_LTD_Manual} (11)	—	15	—	—	15	—	—	μs
t _{LTD_Manual} (12)	—	—	—	4000	—	—	4000	ns
t _{LTD_Auto} (13)	—	—	—	4000	—	—	4000	ns
Receiver CDR 3 dB Bandwidth in lock-to-data (LTD) mode	PCIe Gen1	2.0 - 3.5						MHz
	PCIe Gen2	40 - 65						MHz
	(OIF) CEI PHY at 6.375 Gbps	20 - 35						MHz
	XAUI	10 - 18						MHz
	SRIO 1.25 Gbps	10 - 18						MHz
	SRIO 2.5 Gbps	10 - 18						MHz
	SRIO 3.125 Gbps	6 - 10						MHz
	GIGE	6 - 10						MHz
	SONET OC12	3 - 6						MHz
	SONET OC48	14 - 19						MHz
Receiver buffer and CDR offset cancellation time (per channel)	—	—	—	17000	—	—	17000	recon fig_ clk cycles
Programmable DC gain	DC Gain Setting = 0	—	0	—	—	0	—	dB
	DC Gain Setting = 1	—	3	—	—	3	—	dB
	DC Gain Setting = 2	—	6	—	—	6	—	dB

Table 1-40. Transceiver Block Jitter Specifications for Arria II GX Devices (Note 1) (Part 9 of 10)

Symbol/ Description	Conditions	I3			C4			C5, I5			C6			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
OBSAI Receiver Jitter Tolerance (12)														
Deterministic jitter tolerance at 768 Mbps, 1536 Mbps, and 3072 Mbps	Pattern = CJPAT	> 0.37			> 0.37			> 0.37			> 0.37			UI
Combined deterministic and random jitter tolerance at 768 Mbps, 1536 Mbps, and 3072 Mbps	Pattern = CJPAT	> 0.55			> 0.55			> 0.55			> 0.55			UI
Sinusoidal jitter tolerance at 768 Mbps	Jitter frequency = 5.4 KHz Pattern = CJPAT	> 8.5			> 8.5			> 8.5			> 8.5			UI
	Jitter frequency = 460.8 KHz to 20 MHz Pattern = CJPAT	> 0.1			> 0.1			> 0.1			> 0.1			UI
Sinusoidal jitter tolerance at 1536 Mbps	Jitter frequency = 10.9 KHz Pattern = CJPAT	> 8.5			> 8.5			> 8.5			> 8.5			UI
	Jitter frequency = 921.6 KHz to 20 MHz Pattern = CJPAT	> 0.1			> 0.1			> 0.1			> 0.1			UI

Table 1–41. Transceiver Block Jitter Specifications for Arria II GZ Devices (Note 1), (2) (Part 5 of 7)

Symbol/ Description	Conditions	–C3 and –I3			–C4 and –I4			Unit
		Min	Typ	Max	Min	Typ	Max	
Sinusoidal jitter tolerance (peak-to-peak)	Jitter Frequency = 38.2 KHz Data rate = 6.375 Gbps Pattern = PRBS31 BER = 10 ⁻¹²	> 0.5			—	—	—	UI
	Jitter Frequency = 3.82 MHz Data rate = 6.375 Gbps Pattern = PRBS31 BER = 10 ⁻¹²	> 0.05			—	—	—	UI
	Jitter Frequency = 20 MHz Data rate = 6.375 Gbps Pattern = PRBS31 BER = 10 ⁻¹²	> 0.05			—	—	—	UI
SDI Transmitter Jitter Generation (12)								
Alignment jitter (peak-to-peak)	Data rate = 1.485 Gbps (HD) Pattern = color bar Low-frequency roll-off = 100 KHz	0.2	—	—	0.2	—	—	UI
	Data rate = 2.97 Gbps (3G) Pattern = color bar Low-frequency roll-off = 100 KHz	0.3	—	—	0.3	—	—	UI
SDI Receiver Jitter Tolerance (12)								
Sinusoidal jitter tolerance (peak-to-peak)	Jitter frequency = 15 KHz Data rate = 2.97 Gbps (3G) Pattern = single line scramble color bar	> 2			> 2			UI
	Jitter frequency = 100 KHz Data rate = 2.97 Gbps (3G) Pattern = single line scramble color bar	> 0.3			> 0.3			UI
	Jitter frequency = 148.5 MHz Data rate = 2.97 Gbps (3G) Pattern = single line scramble color bar	> 0.3			> 0.3			UI
Sinusoidal jitter tolerance (peak-to-peak)	Jitter frequency = 20 KHz Data rate = 1.485 Gbps (HD) pattern = 75% color bar	> 1			> 1			UI
	Jitter frequency = 100 KHz Data rate = 1.485 Gbps (HD) Pattern = 75% color bar	> 0.2			> 0.2			UI
	Jitter frequency = 148.5 MHz Data rate = 1.485 Gbps (HD) Pattern = 75% color bar	> 0.2			> 0.2			UI
SAS Transmit Jitter Generation (13)								
Total jitter at 1.5 Gbps (G1)	Pattern = CJPAT	—	—	0.55	—	—	0.55	UI
Deterministic jitter at 1.5 Gbps (G1)	Pattern = CJPAT	—	—	0.35	—	—	0.35	UI
Total jitter at 3.0 Gbps (G2)	Pattern = CJPAT	—	—	0.55	—	—	0.55	UI

Table 1–41. Transceiver Block Jitter Specifications for Arria II GZ Devices (Note 1), (2) (Part 7 of 7)

Symbol/ Description	Conditions	–C3 and –I3			–C4 and –I4			Unit
		Min	Typ	Max	Min	Typ	Max	
OBSAI Receiver Jitter Tolerance (15)								
Deterministic jitter tolerance at 768 Mbps, 1536 Mbps, and 3072 Mbps	Pattern = CJPAT	> 0.37			> 0.37			UI
Combined deterministic and random jitter tolerance at 768 Mbps, 1536 Mbps, and 3072 Mbps	Pattern = CJPAT	> 0.55			> 0.55			UI
Sinusoidal jitter tolerance at 768 Mbps	Jitter frequency = 5.4 KHz Pattern = CJPAT	> 8.5			> 8.5			UI
	Jitter frequency = 460 MHz to 20 MHz Pattern = CJPAT	> 0.1			> 0.1			UI
Sinusoidal jitter tolerance at 1536 Mbps	Jitter frequency = 10.9 KHz Pattern = CJPAT	> 8.5			> 8.5			UI
	Jitter frequency = 921.6 MHz to 20 MHz Pattern = CJPAT	> 0.1			> 0.1			UI
Sinusoidal jitter tolerance at 3072 Mbps	Jitter frequency = 21.8 KHz Pattern = CJPAT	> 8.5			> 8.5			UI
	Jitter frequency = 1843.2 MHz to 20 MHz Pattern = CJPAT	> 0.1			> 0.1			UI

Notes to Table 1–41:

- (1) Dedicated `refclk` pins were used to drive the input reference clocks.
- (2) The jitter numbers are valid for the stated conditions only.
- (3) The jitter numbers for SONET/SDH are compliant to the GR-253-CORE Issue 3 Specification.
- (4) The jitter numbers for Fibre Channel are compliant to the FC-P1-4 Specification revision 6.10.
- (5) The Fibre Channel transmitter jitter generation numbers are compliant to the specification at the δ_T inter operability point.
- (6) The Fibre Channel receiver jitter tolerance numbers are compliant to the specification at the δ_R interpretability point.
- (7) The jitter numbers for XAUI are compliant to the IEEE802.3ae-2002 Specification.
- (8) The jitter numbers for PCIe are compliant to the PCIe Base Specification 2.0.
- (9) Arria II GZ PCIe receivers are compliant to this specification provided the $V_{TX-CM-DC-ACTIVEIDLE-DELTA}$ of the upstream transmitter is less than 50 mV.
- (10) The jitter numbers for SRIO are compliant to the RapidIO Specification 1.3.
- (11) The jitter numbers for GIGE are compliant to the IEEE802.3-2002 Specification.
- (12) The HD-SDI and 3G-SDI jitter numbers are compliant to the SMPTE292M and SMPTE424M Specifications.
- (13) The jitter numbers for Serial Attached SCSI (SAS) are compliant to the SAS-2.1 Specification.
- (14) The jitter numbers for CPRI are compliant to the CPRI Specification V3.0.
- (15) The jitter numbers for OBSAI are compliant to the OBSAI RP3 Specification V4.1.

Table 1-44. PLL Specifications for Arria II GX Devices (Part 3 of 3)

Symbol	Description	Min	Typ	Max	Unit
$t_{CASC_OUTJITTER_PERIOD_DEDCLK}$ (6), (7)	Period jitter for dedicated clock output in cascaded PLLs ($F_{OUT} \geq 100$ MHz)	—	—	425	ps (p-p)
	Period jitter for dedicated clock output in cascaded PLLs ($F_{OUT} \leq 100$ MHz)	—	—	42.5	mUI (p-p)

Notes to Table 1-44:

- (1) f_{IN} is limited by the I/O f_{MAX} .
- (2) The VCO frequency reported by the Quartus II software in the PLL summary section of the compilation report takes into consideration the VCO post-scale counter K value. Therefore, if the counter K has a value of 2, the frequency reported can be lower than the f_{VCO} specification.
- (3) A high-input jitter directly affects the PLL output jitter. To have low PLL output clock jitter, you must provide a clean-clock source, which is less than 200 ps.
- (4) F_{REF} is f_{IN}/N when $N = 1$.
- (5) This specification is limited by the lower of the two: I/O f_{MAX} or f_{OUT} of the PLL.
- (6) Peak-to-peak jitter with a probability level of 10^{-12} (14 sigma, 99.9999999974404% confidence level). The output jitter specification applies to the intrinsic jitter of the PLL, when an input jitter of 30 ps is applied. The external memory interface clock output jitter specifications use a different measurement method and are available in Table 1-62 on page 1-70.
- (7) The cascaded PLL specification is only applicable with the following condition:
 - a. Upstream PLL: $0.59 \text{ MHz} \leq \text{Upstream PLL BW} < 1 \text{ MHz}$
 - b. Downstream PLL: $\text{Downstream PLL BW} > 2 \text{ MHz}$

Table 1-45 lists the PLL specifications for Arria II GZ devices when operating in both the commercial junction temperature range (0° to 85°C) and the industrial junction temperature range (-40° to 100°C).

Table 1-45. PLL Specifications for Arria II GZ Devices (Part 1 of 2)

Symbol	Parameter	Min	Typ	Max	Unit
f_{IN}	Input clock frequency (-3 speed grade)	5	—	717 (1)	MHz
	Input clock frequency (-4 speed grade)	5	—	717 (1)	MHz
f_{INPFD}	Input frequency to the PFD	5	—	325	MHz
f_{VCO}	PLL VCO operating range (-3 speed grade)	600	—	1,300	MHz
	PLL VCO operating range (-4 speed grade)	600	—	1,300	MHz
$t_{EINDUTY}$	Input clock or external feedback clock input duty cycle	40	—	60	%
f_{OUT}	Output frequency for internal global or regional clock (-3 speed grade)	—	—	700 (2)	MHz
	Output frequency for internal global or regional clock (-4 speed grade)	—	—	500 (2)	MHz
f_{OUT_EXT}	Output frequency for external clock output (-3 speed grade)	—	—	717 (2)	MHz
	Output frequency for external clock output (-4 speed grade)	—	—	717 (2)	MHz
$t_{OUTDUTY}$	Duty cycle for external clock output (when set to 50%)	45	50	55	%
t_{FCOMP}	External feedback clock compensation time	—	—	10	ns
$t_{CONFIGPLL}$	Time required to reconfigure scan chain	—	3.5	—	scanclk cycles
$t_{CONFIGPHASE}$	Time required to reconfigure phase shift	—	1	—	scanclk cycles
$f_{SCANCLK}$	scanclk frequency	—	—	100	MHz
t_{LOCK}	Time required to lock from end-of-device configuration or de-assertion of areset	—	—	1	ms

Table 1-45. PLL Specifications for Arria II GZ Devices (Part 2 of 2)

Symbol	Parameter	Min	Typ	Max	Unit
t_{DLOCK}	Time required to lock dynamically (after switchover or reconfiguring any non-post-scale counters/delays)	—	—	1	ms
f_{CLBW}	PLL closed-loop low bandwidth	—	0.3	—	MHz
	PLL closed-loop medium bandwidth	—	1.5	—	MHz
	PLL closed-loop high bandwidth (7)	—	4	—	MHz
$t_{\text{PLL_PSERR}}$	Accuracy of PLL phase shift	—	—	±50	ps
t_{ARESET}	Minimum pulse width on the areset signal	10	—	—	ns
t_{INCCJ} (3), (4)	Input clock cycle to cycle jitter ($F_{\text{REF}} \geq 100$ MHz)	—	—	0.15	UI (p-p)
	Input clock cycle to cycle jitter ($F_{\text{REF}} < 100$ MHz)	—	—	±750	ps (p-p)
$t_{\text{OUTPJ_DC}}$ (5)	Period Jitter for dedicated clock output ($F_{\text{OUT}} \geq 100$ MHz)	—	—	175	ps (p-p)
	Period Jitter for dedicated clock output ($F_{\text{OUT}} < 100$ MHz)	—	—	17.5	mUI (p-p)
$t_{\text{OUTCCJ_DC}}$ (5)	Cycle to Cycle Jitter for dedicated clock output ($F_{\text{OUT}} \geq 100$ MHz)	—	—	175	ps (p-p)
	Cycle to Cycle Jitter for dedicated clock output ($F_{\text{OUT}} < 100$ MHz)	—	—	17.5	mUI (p-p)
$t_{\text{OUTPJ_IO}}$ (5), (8)	Period Jitter for clock output on regular I/O ($F_{\text{OUT}} \geq 100$ MHz)	—	—	600	ps (p-p)
	Period Jitter for clock output on regular I/O ($F_{\text{OUT}} < 100$ MHz)	—	—	60	mUI (p-p)
$t_{\text{OUTCCJ_IO}}$ (5), (8)	Cycle to Cycle Jitter for clock output on regular I/O ($F_{\text{OUT}} \geq 100$ MHz)	—	—	600	ps (p-p)
	Cycle to Cycle Jitter for clock output on regular I/O ($F_{\text{OUT}} < 100$ MHz)	—	—	60	mUI (p-p)
$t_{\text{CASC_OUTPJ_DC}}$ (5), (6)	Period Jitter for dedicated clock output in cascaded PLLs ($F_{\text{OUT}} \geq 100$ MHz)	—	—	250	ps (p-p)
	Period Jitter for dedicated clock output in cascaded PLLs ($F_{\text{OUT}} < 100$ MHz)	—	—	25	mUI (p-p)
f_{DRIFT}	Frequency drift after PFDENA is disabled for duration of 100 μ s	—	—	±10	%

Notes to Table 1-45:

- (1) This specification is limited in the Quartus II software by the I/O maximum frequency. The maximum I/O frequency is different for each I/O standard.
- (2) This specification is limited by the lower of the two: I/O F_{MAX} or F_{OUT} of the PLL.
- (3) A high input jitter directly affects the PLL output jitter. To have low PLL output clock jitter, you must provide a clean clock source that is less than 120 ps.
- (4) F_{REF} is f_{IN}/N when $N = 1$.
- (5) Peak-to-peak jitter with a probability level of 10^{-12} (14 sigma, 99.9999999974404% confidence level). The output jitter specification applies to the intrinsic jitter of the PLL, when an input jitter of 30 ps is applied. The external memory interface clock output jitter specifications use a different measurement method and are available in [Table 1-64 on page 1-71](#).
- (6) The cascaded PLL specification is only applicable with the following condition:
 - a. Upstream PLL: $0.59 \text{ MHz} \leq \text{Upstream PLL BW} < 1 \text{ MHz}$
 - b. Downstream PLL: $\text{Downstream PLL BW} > 2 \text{ MHz}$
- (7) High bandwidth PLL settings are not supported in external feedback mode.
- (8) External memory interface clock output jitter specifications use a different measurement method, which is available in [Table 1-63 on page 1-71](#).

DSP Block Specifications

Table 1-46 lists the DSP block performance specifications for Arria II GX devices.

Table 1-46. DSP Block Performance Specifications for Arria II GX Devices (Note 1)

Mode	Resources Used	Performance				Unit
	Number of Multipliers	C4	I3	C5,I5	C6	
9 × 9-bit multiplier	1	380	310	300	250	MHz
12 × 12-bit multiplier	1	380	310	300	250	MHz
18 × 18-bit multiplier	1	380	310	300	250	MHz
36 × 36-bit multiplier	1	350	270	270	220	MHz
18 × 36-bit high-precision multiplier adder mode	1	350	270	270	220	MHz
18 × 18-bit multiply accumulator	4	380	310	300	250	MHz
18 × 18-bit multiply adder	4	380	310	300	250	MHz
18 × 18-bit multiply adder-signed full precision	2	380	310	300	250	MHz
18 × 18-bit multiply adder with loopback (2)	2	275	220	220	180	MHz
36-bit shift (32-bit data)	1	350	270	270	220	MHz
Double mode	1	350	270	270	220	MHz

Notes to Table 1-46:

- (1) Maximum is for a fully-pipelined block with **Round** and **Saturation** disabled.
- (2) Maximum is for loopback input registers disabled, **Round** and **Saturation** disabled, pipeline and output registers enabled.

Table 1-47 lists the DSP block performance specifications for Arria II GZ devices.

Table 1-47. DSP Block Performance Specifications for Arria II GZ Devices (Note 1) (Part 1 of 2)

Mode	Resources Used	Performance		Unit
	Number of Multipliers	-3	-4	
9 × 9-bit multiplier	1	460	400	MHz
12 × 12-bit multiplier	1	500	440	MHz
18 × 18-bit multiplier	1	550	480	MHz
36 × 36-bit multiplier	1	440	380	MHz
18 × 18-bit multiply accumulator	4	440	380	MHz
18 × 18-bit multiply adder	4	470	410	MHz
18 × 18-bit multiply adder-signed full precision	2	450	390	MHz
18 × 18-bit multiply adder with loopback (2)	2	350	310	MHz
36-bit shift (32-bit data)	1	440	380	MHz

Table 1–47. DSP Block Performance Specifications for Arria II GZ Devices (Note 1) (Part 2 of 2)

Mode	Resources Used	Performance		Unit
	Number of Multipliers	–3	–4	
Double mode	1	440	380	MHz

Notes to Table 1–47:

- (1) Maximum is for fully pipelined block with **Round** and **Saturation** disabled.
- (2) Maximum for loopback input registers disabled, **Round** and **Saturation** disabled, and pipeline and output registers enabled.

Embedded Memory Block Specifications

Table 1–48 lists the embedded memory block specifications for Arria II GX devices.

Table 1–48. Embedded Memory Block Performance Specifications for Arria II GX Devices

Memory	Mode	Resources Used		Performance				Unit
		ALUTs	Embedded Memory	I3	C4	C5,I5	C6	
Memory Logic Array Block (MLAB)	Single port 64 × 10	0	1	450	500	450	378	MHz
	Simple dual-port 32 × 20 single clock	0	1	270	500	450	378	MHz
	Simple dual-port 64 × 10 single clock	0	1	428	500	450	378	MHz
M9K Block	Single-port 256 × 36	0	1	360	400	360	310	MHz
	Single-port 256 × 36, with the read-during-write option set to Old Data	0	1	250	280	250	210	MHz
	Simple dual-port 256 × 36 single CLK	0	1	360	400	360	310	MHz
	Single-port 256 × 36 single CLK, with the read-during-write option set to Old Data	0	1	250	280	250	210	MHz
	True dual port 512 × 18 single CLK	0	1	360	400	360	310	MHz
	True dual-port 512 × 18 single CLK, with the read-during-write option set to Old Data	0	1	250	280	250	210	MHz
	Min Pulse Width (clock high time)	—	—	900	850	950	1130	ps
	Min Pulse Width (clock low time)	—	—	730	690	770	920	ps

Configuration

Table 1–50 lists the configuration mode specifications for Arria II GX and GZ devices.

Table 1–50. Configuration Mode Specifications for Arria II Devices

Programming Mode	DCLK Frequency			Unit
	Min	Typ	Max	
Passive serial	—	—	125	MHz
Fast passive parallel	—	—	125	MHz
Fast active serial (fast clock)	17	26	40	MHz
Fast active serial (slow clock)	8.5	13	20	MHz
Remote update only in fast AS mode	—	—	10	MHz

JTAG Specifications

Table 1–51 lists the JTAG timing parameters and values for Arria II GX and GZ devices.

Table 1–51. JTAG Timing Parameters and Values for Arria II Devices

Symbol	Description	Min	Max	Unit
t_{JCP}	TCK clock period	30	—	ns
t_{JCH}	TCK clock high time	14	—	ns
t_{JCL}	TCK clock low time	14	—	ns
$t_{JPSU(TDI)}$	TDI JTAG port setup time	1	—	ns
$t_{JPSU(TMS)}$	TMS JTAG port setup time	3	—	ns
t_{JPH}	JTAG port hold time	5	—	ns
t_{JPCO}	JTAG port clock to output	—	11	ns
t_{JPZX}	JTAG port high impedance to valid output	—	14	ns
t_{JPXZ}	JTAG port valid output to high impedance	—	14	ns

Chip-Wide Reset (Dev_CLRn) Specifications

Table 1–52 lists the specifications for the chip-wide reset (Dev_CLRn) for Arria II GX and GZ devices.

Table 1–52. Chip-Wide Reset (Dev_CLRn) Specifications for Arria II Devices

Description	Min	Typ	Max	Unit
Dev_CLRn	500	—	—	μ s

Table 1-53. High-Speed I/O Specifications for Arria II GX Devices (Part 3 of 4)

Symbol	Conditions	I3		C4		C5,I5		C6		Unit
		Min	Max	Min	Max	Min	Max	Min	Max	
t_{TX_JITTER} (4)	True LVDS with dedicated SERDES (data rate 600–1,250 Mbps)	—	175	—	175	—	225	—	300	ps
	True LVDS with dedicated SERDES (data rate < 600 Mbps)	—	0.105	—	0.105	—	0.135	—	0.18	UI
	True LVDS and emulated LVDS_E_3R with logic elements as SERDES (data rate 600 – 945 Mbps)	—	260	—	260	—	300	—	350	ps
	True LVDS and emulated LVDS_E_3R with logic elements as SERDES (data rate < 600 Mbps)	—	0.16	—	0.16	—	0.18	—	0.21	UI
t_{TX_DCD}	True LVDS and emulated LVDS_E_3R	45	55	45	55	45	55	45	55	%
t_{RISE} and t_{FALL}	True LVDS and emulated LVDS_E_3R	—	200	—	200	—	225	—	250	ps
TCCS	True LVDS (5)	—	150	—	150	—	175	—	200	ps
	Emulated LVDS_E_3R	—	200	—	200	—	250	—	300	ps
Receiver (6)										
True differential I/O standards - f_{HSDRPA} (data rate)	SERDES factor J = 3 to 10	150	1250	150	1250	150	1050	150	840	Mbps

Table 1-54. High-Speed I/O Specifications for Arria II GZ Devices (Note 1), (2), (10) (Part 2 of 3)

Symbol	Conditions	C3, I3			C4, I4			Unit
		Min	Typ	Max	Min	Typ	Max	
$f_{\text{HCLK_OUT}}$ (output clock frequency)	—	5	—	717 (7)	5	—	717 (7)	MHz
Transmitter								
f_{HSDR} (true LVDS output data rate)	SERDES factor, J = 3 to 10 (using dedicated SERDES) (8)	(4)	—	1250	(4)	—	1250	Mbps
	SERDES factor J = 2, (using DDR registers)	(4)	—	(5)	(4)	—	(5)	Mbps
	SERDES factor J = 1, (uses an SDR register)	(4)	—	(5)	(4)	—	(5)	Mbps
f_{HSDR} (emulated LVDS_E_3R output data rate) (5)	SERDES factor J = 4 to 10	(4)	—	1152	(4)	—	800	Mbps
f_{HSDR} (emulated LVDS_E_1R output data rate)		(4)	—	200	(4)	—	200	Mbps
$t_{\text{x Jitter}}$	Total jitter for data rate, 600 Mbps to 1.6 Gbps	—	—	160	—	—	160	ps
	Total jitter for data rate, < 600 Mbps	—	—	0.1	—	—	0.1	UI
$t_{\text{x Jitter}}$ - emulated differential I/O standards with three external output resistor network	Total jitter for data rate, 600 Mbps to 1.25 Gbps	—	—	300	—	—	325	ps
	Total jitter for data rate < 600 Mbps	—	—	0.2	—	—	0.25	UI
$t_{\text{x Jitter}}$ - emulated differential I/O standards with one external output resistor network	—	—	—	0.15	—	—	0.15	UI
t_{DUTY}	TX output clock duty cycle for both True and emulated differential I/O standards	45	50	55	45	50	55	%

Table 1–54. High-Speed I/O Specifications for Arria II GZ Devices (Note 1), (2), (10) (Part 3 of 3)

Symbol	Conditions	C3, I3			C4, I4			Unit
		Min	Typ	Max	Min	Typ	Max	
$t_{RISE} \text{ \& } t_{FALL}$	True differential I/O standards	—	—	200	—	—	200	ps
	Emulated differential I/O standards with three external output resistor networks	—	—	250	—	—	300	ps
	Emulated differential I/O standards with one external output resistor	—	—	500	—	—	500	ps
TCCS	True LVDS	—	—	100	—	—	100	ps
	Emulated LVDS_E_3R	—	—	250	—	—	250	ps
Receiver								
True differential I/O standards - f_{HSDRDA} (data rate)	SERDES factor J = 3 to 10	150	—	1250	150	—	1250	Mbps
f_{HSDR} (data rate)	SERDES factor J = 3 to 10	(4)	—	(6)	(4)	—	(6)	Mbps
	SERDES factor J = 2, uses DDR registers	(4)	—	(5)	(4)	—	(5)	Mbps
	SERDES factor J = 1, uses an SDR register	(4)	—	(5)	(4)	—	(5)	Mbps
DPA run length	DPA mode	—	—	10000	—	—	10000	UI
Soft-CDR PPM tolerance	Soft-CDR mode	—	—	300	—	—	300	± PPM
Sampling Window (SW)	Non-DPA mode	—	—	300	—	—	300	ps

Notes to Table 1–54:

- (1) When J = 3 to 10, use the SERDES block.
- (2) When J = 1 or 2, bypass the SERDES block.
- (3) Clock Boost Factor (W) is the ratio between input data rate to the input clock rate.
- (4) The minimum specification depends on the clock source (for example, the PLL and clock pin) and the clock routing resource (global, regional, or local) that you use. The I/O differential buffer and input register do not have a minimum toggle rate.
- (5) You must calculate the leftover timing margin in the receiver by performing link timing closure analysis. You must consider the board skew margin, transmitter channel-to-channel skew, and receiver sampling margin to determine leftover timing margin.
- (6) You can estimate the achievable maximum data rate for non-DPA mode by performing link timing closure analysis. You must consider the board skew margin, transmitter delay margin, and the receiver sampling margin to determine the maximum data rate supported.
- (7) This is achieved by using the LVDS and DPA clock network.
- (8) If the receiver with DPA enabled and transmitter are using shared PLLs, the minimum data rate is 150 Mbps.
- (9) This only applies to DPA and soft-CDR modes.
- (10) This only applies to LVDS source synchronous mode.

Table 1–55 lists DPA lock time specifications for Arria II GX and GZ devices.

I/O Timing

Altera offers two ways to determine I/O timing:

- Using the Microsoft Excel-based I/O Timing.
- Using the Quartus II Timing Analyzer.

The Microsoft Excel-based I/O Timing provides pin timing performance for each device density and speed grade. The data is typically used prior to designing the FPGA to get an estimate of the timing budget as part of the link timing analysis. The Quartus II timing analyzer provides a more accurate and precise I/O timing data based on the specifics of the design after place-and-route is complete.



The Microsoft Excel-based I/O Timing spreadsheet is downloadable from the [Literature: Arria II Devices](#) web page.